

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB330P10NM	**Issued**	08. April 2022
MA#	MA005710429		
Package	PG-TO263-3-2	**Weight***	1567.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.330	0.79	0.79	7866	7866
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.39	19.42	193942	194194
wire	non noble metal	aluminium	7429-90-5	13.833	0.88	0.88	8824	8824
encapsulation	inorganic material	zincoxide	1314-13-2	6.709	0.43		4280	
	miscellaneous	miscellaneous	-	26.837	1.71		17120	
	plastics	epoxy resin	-	100.639	6.42		64199	
	inorganic material	silicondioxide	60676-86-0	536.741	34.24	42.80	342395	427994
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6160	6160
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.157	0.01		100	
	noble metal	silver	7440-22-4	0.196	0.01		125	
	non noble metal	lead	7439-92-1	7.483	0.48	0.50	4773	4998
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.93	34.98	349362	349817
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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